

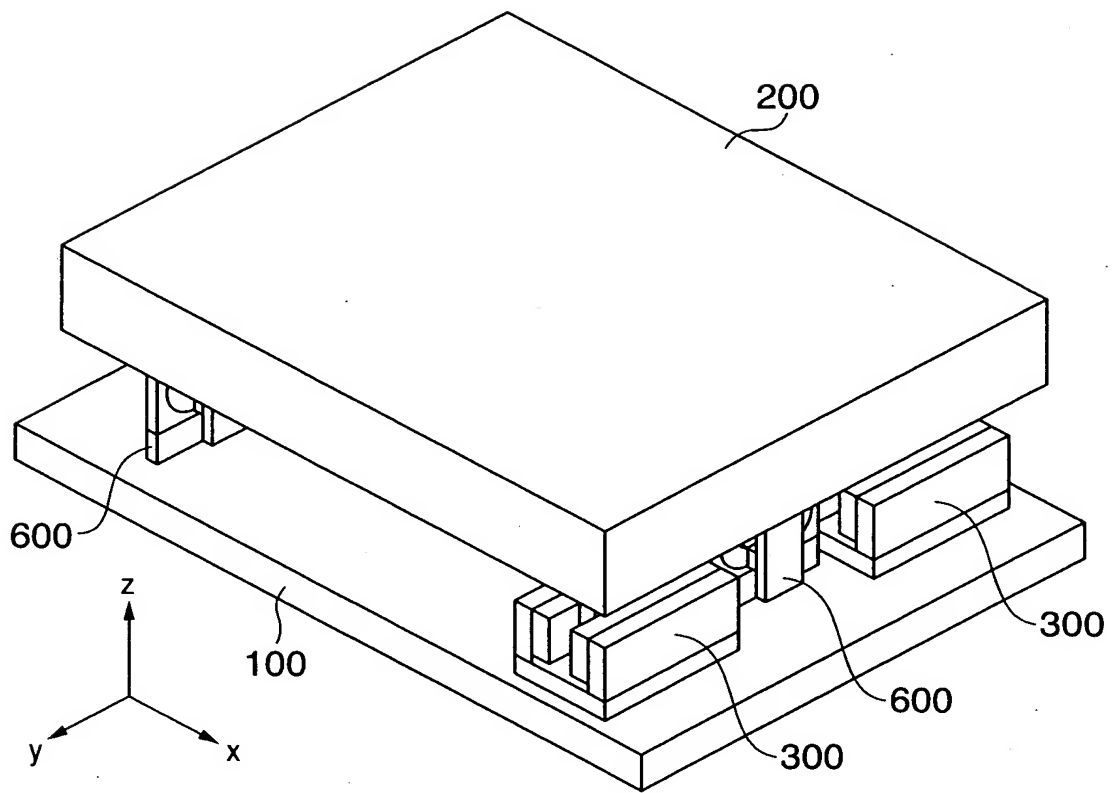
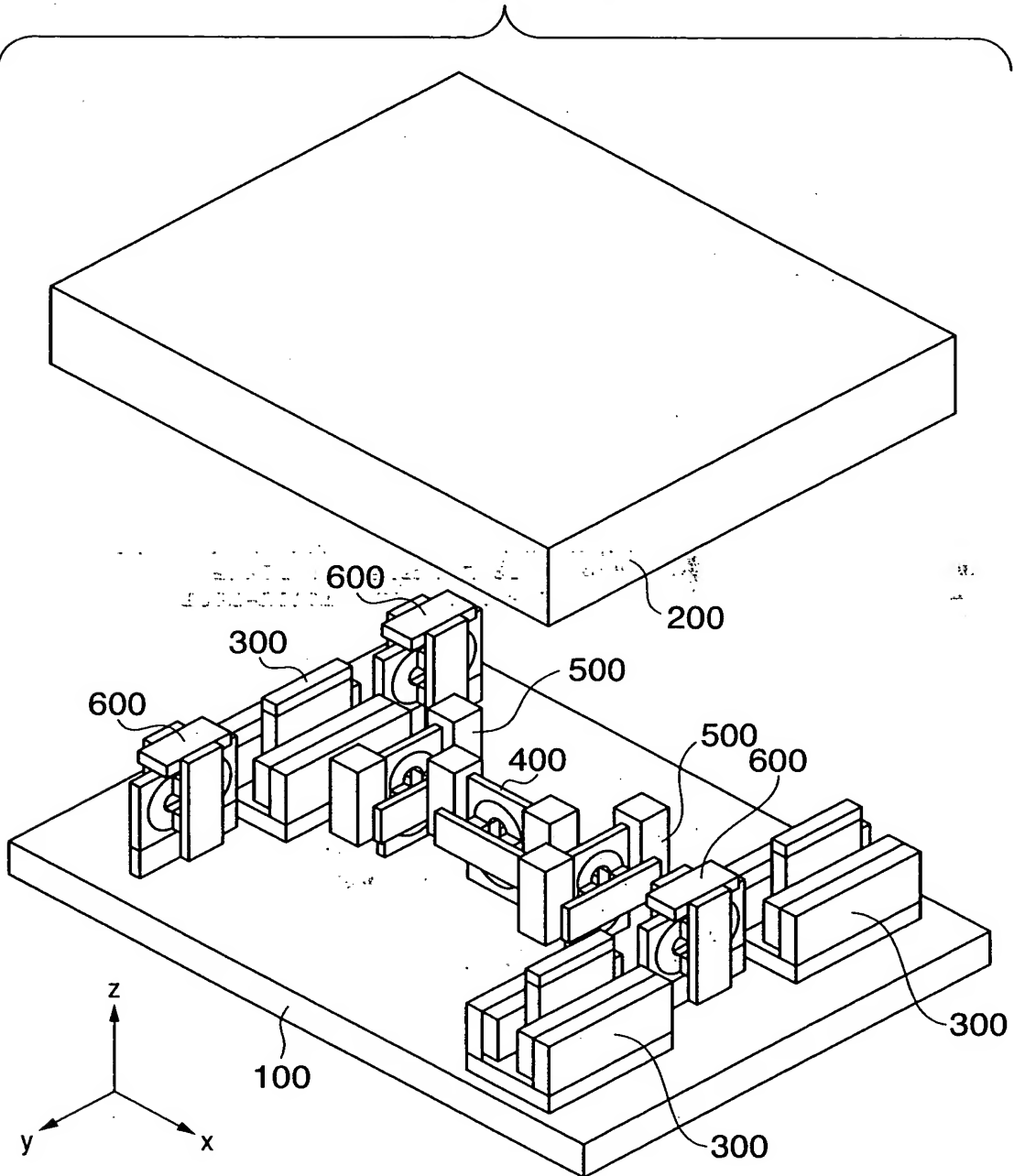
FIG. 1

FIG. 2

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FIG. 3A

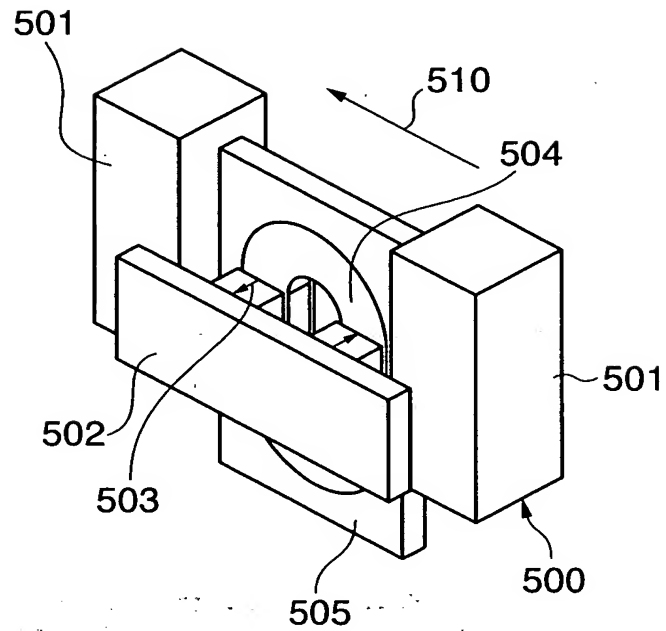


FIG. 3B

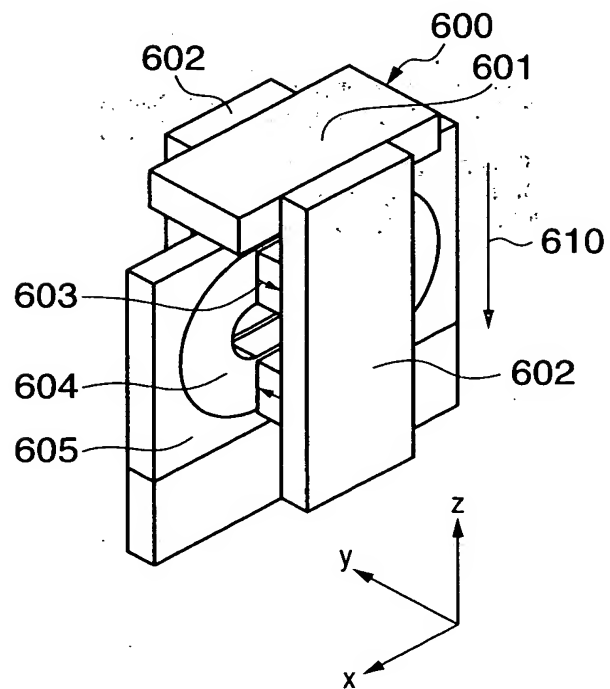


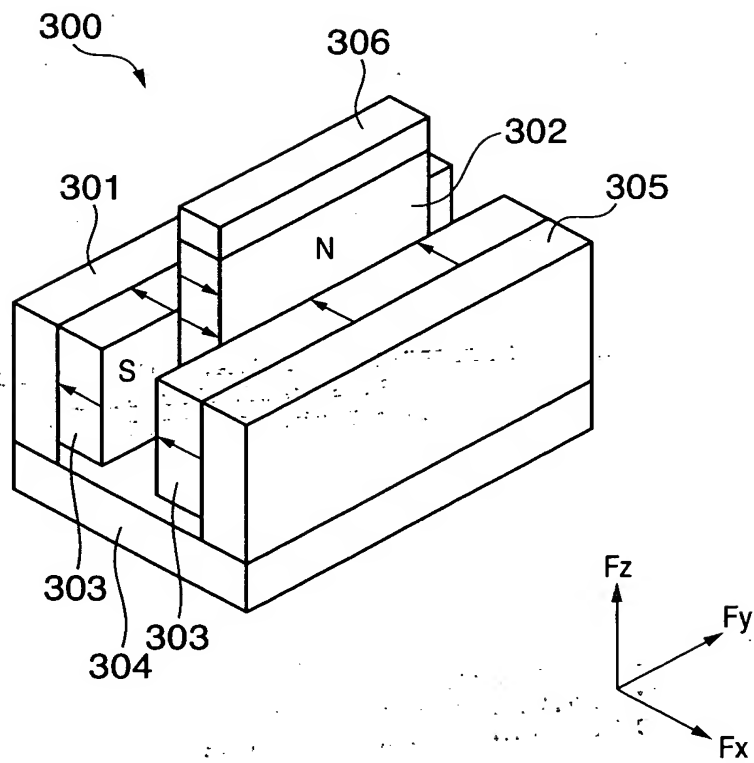
FIG. 4A

FIG. 4B

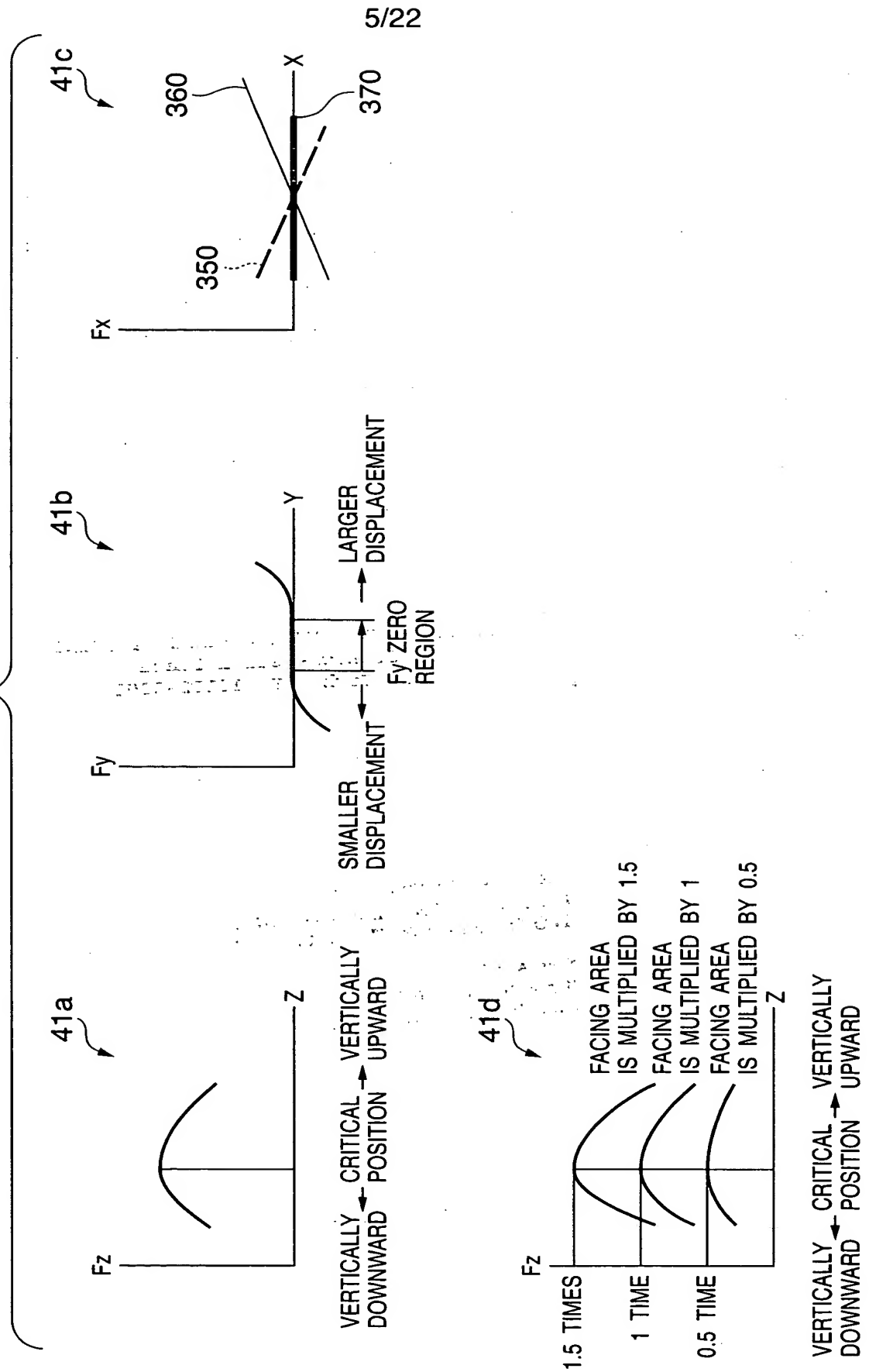


FIG. 5

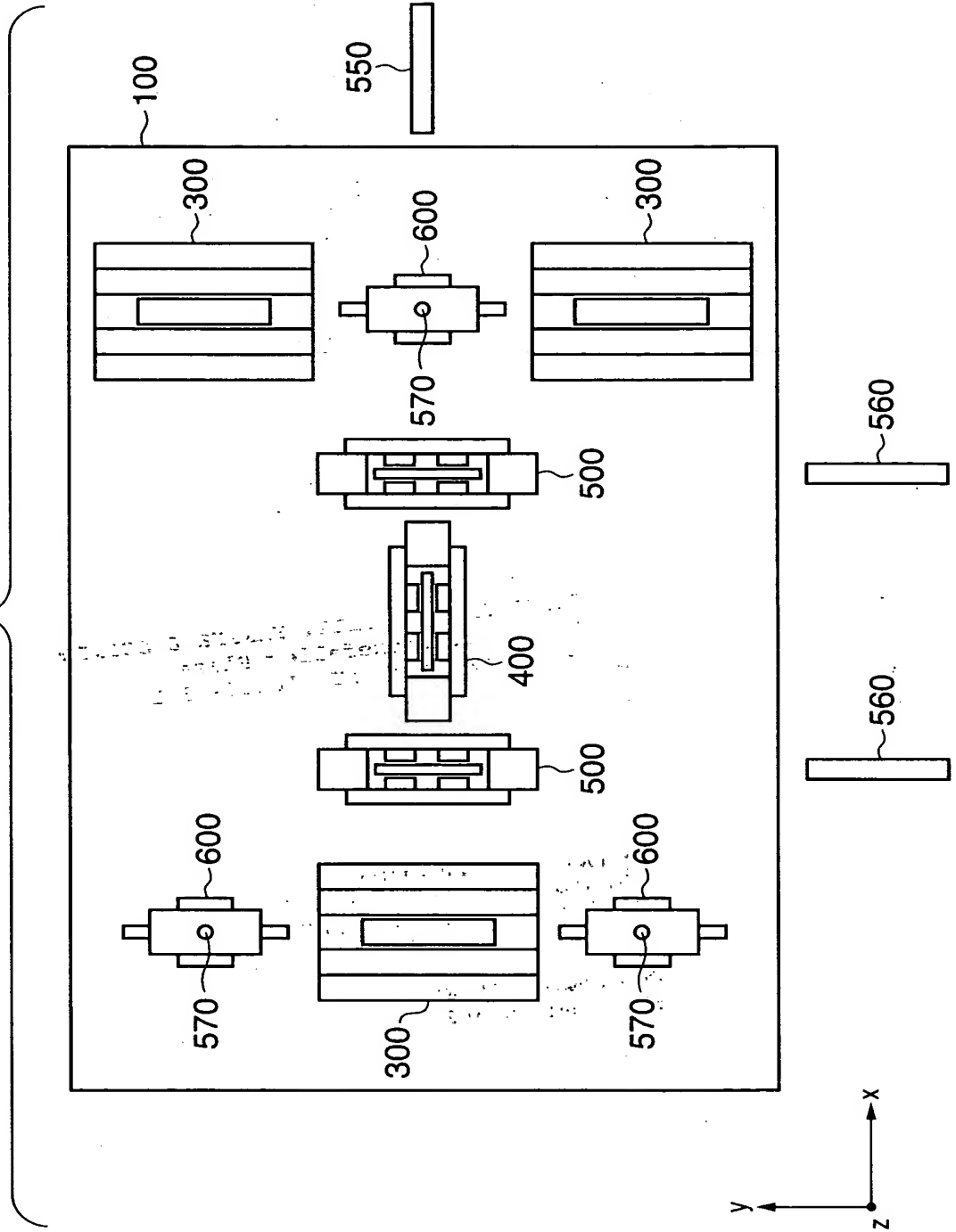
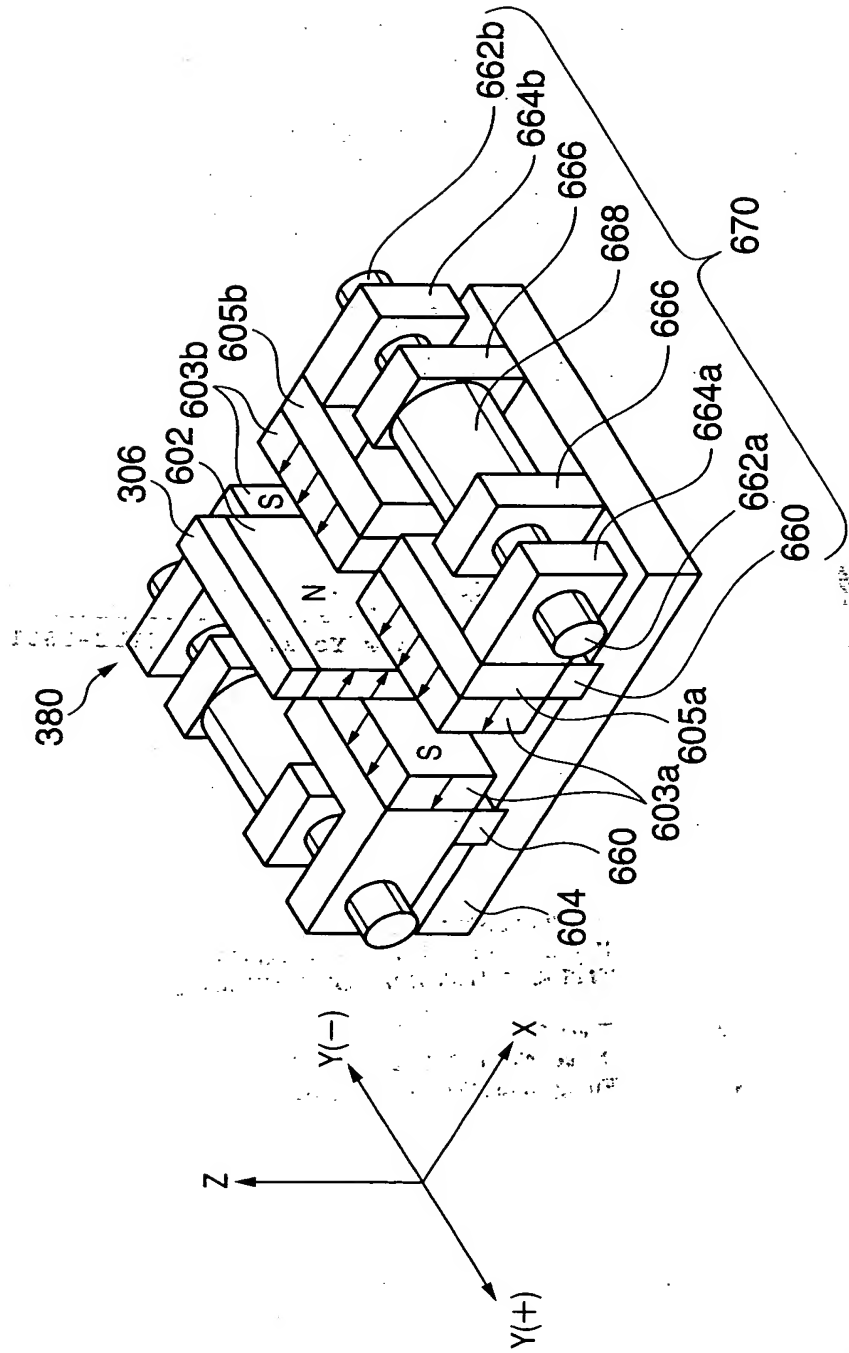


FIG. 6A



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FIG. 6B

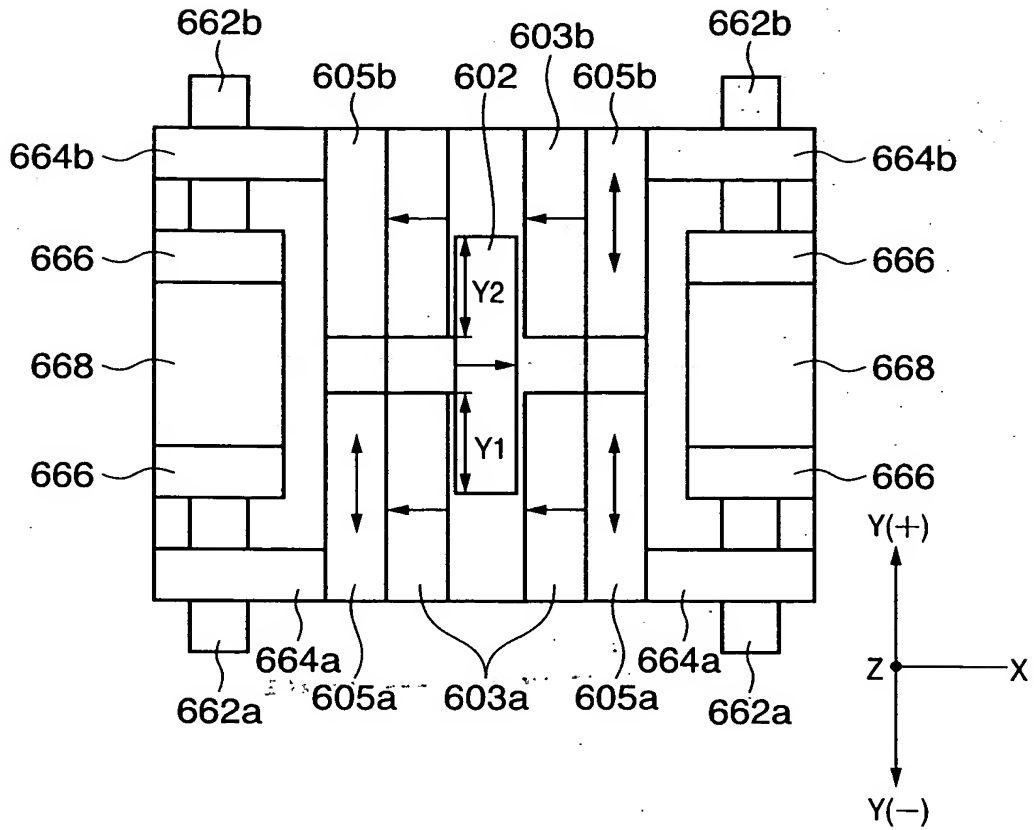


FIG. 6C

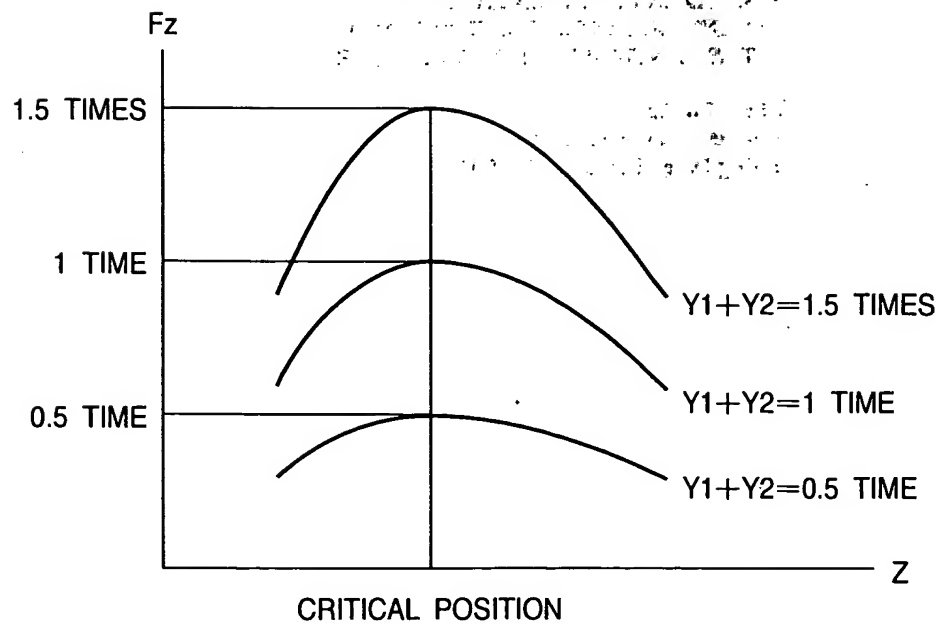


FIG. 6D

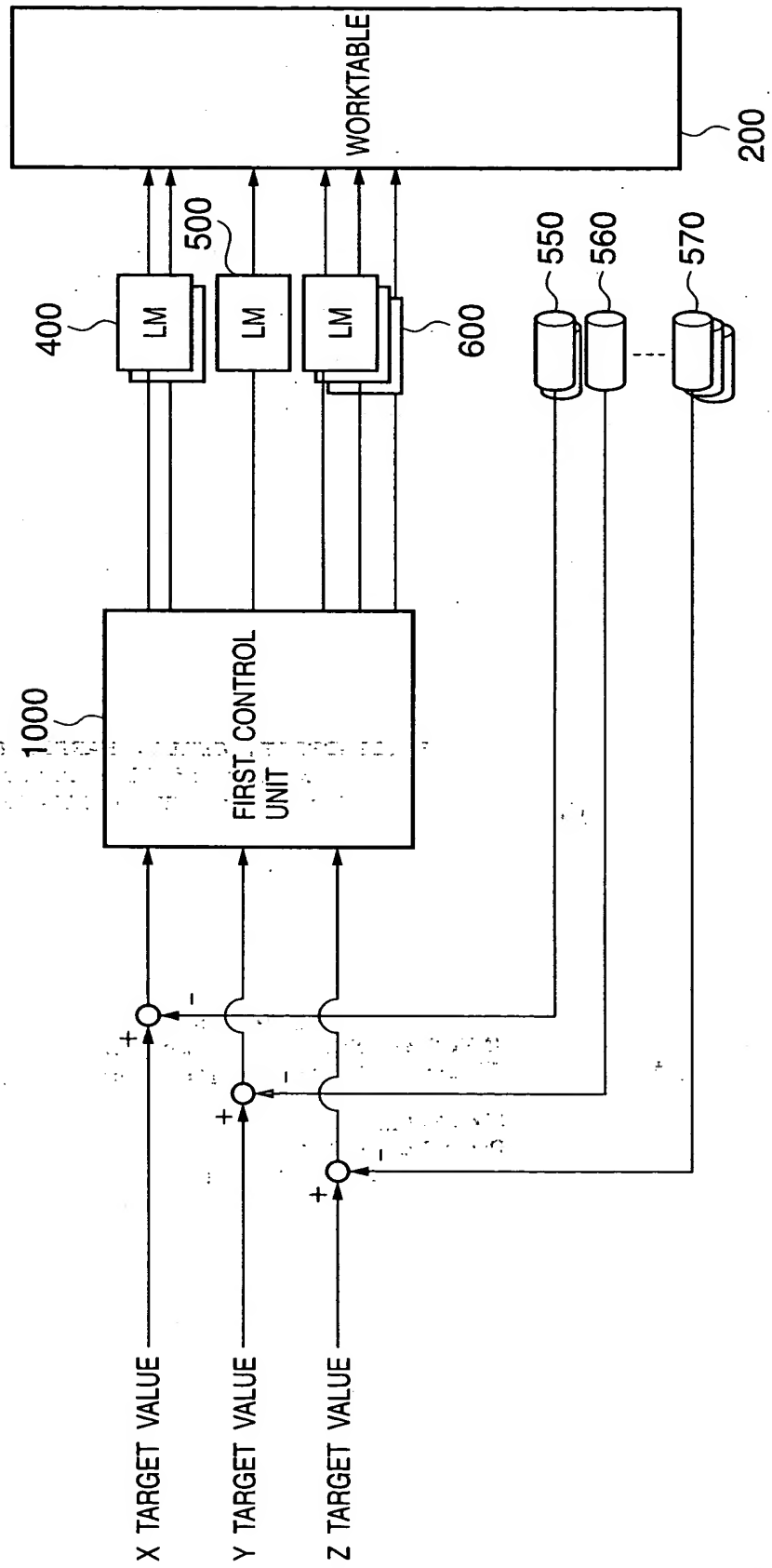
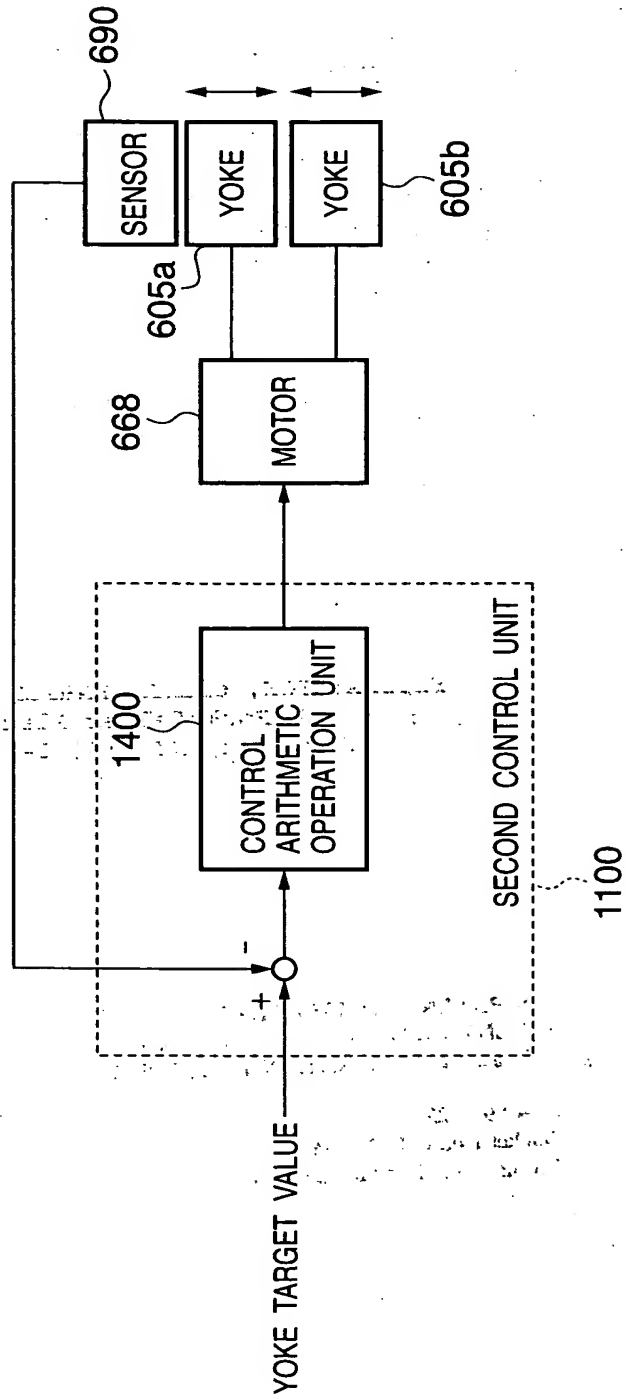
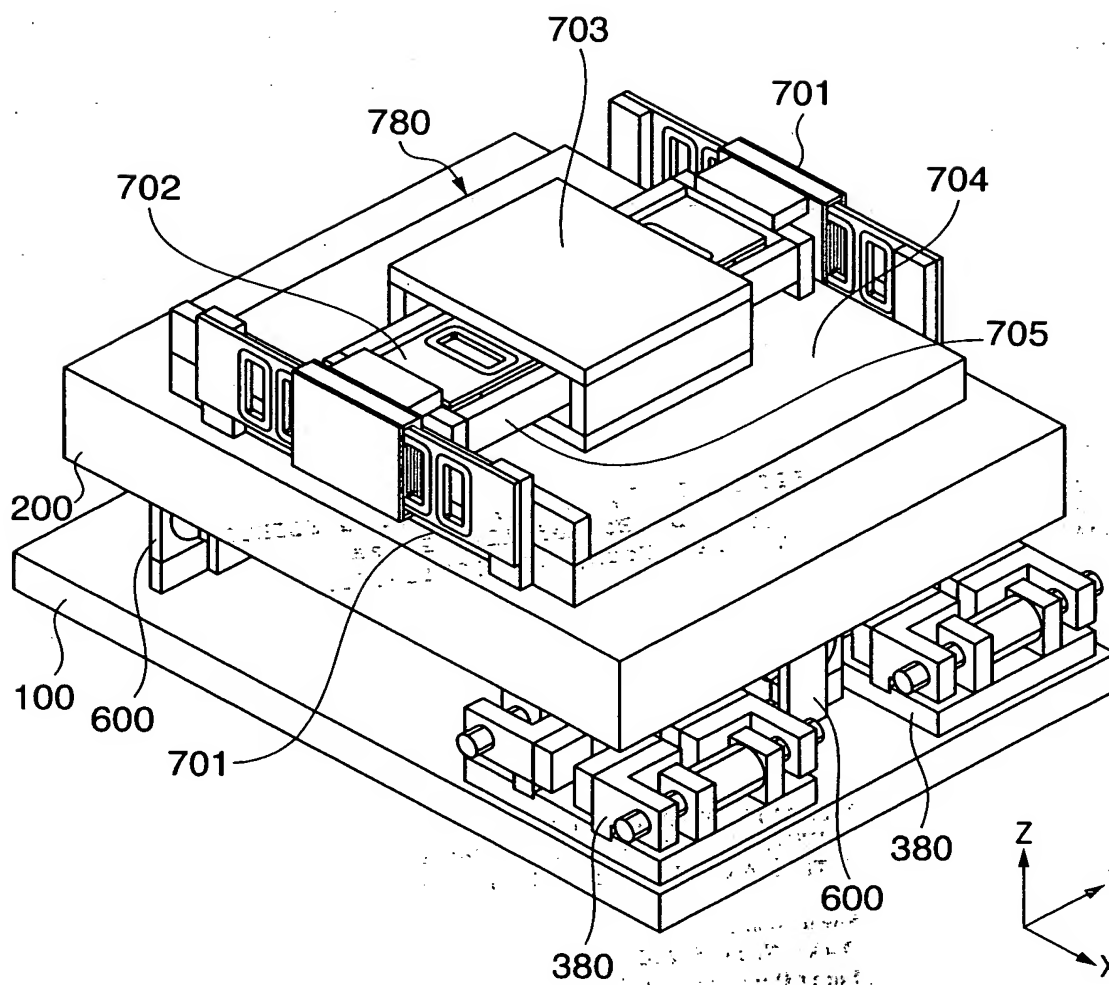


FIG. 6E





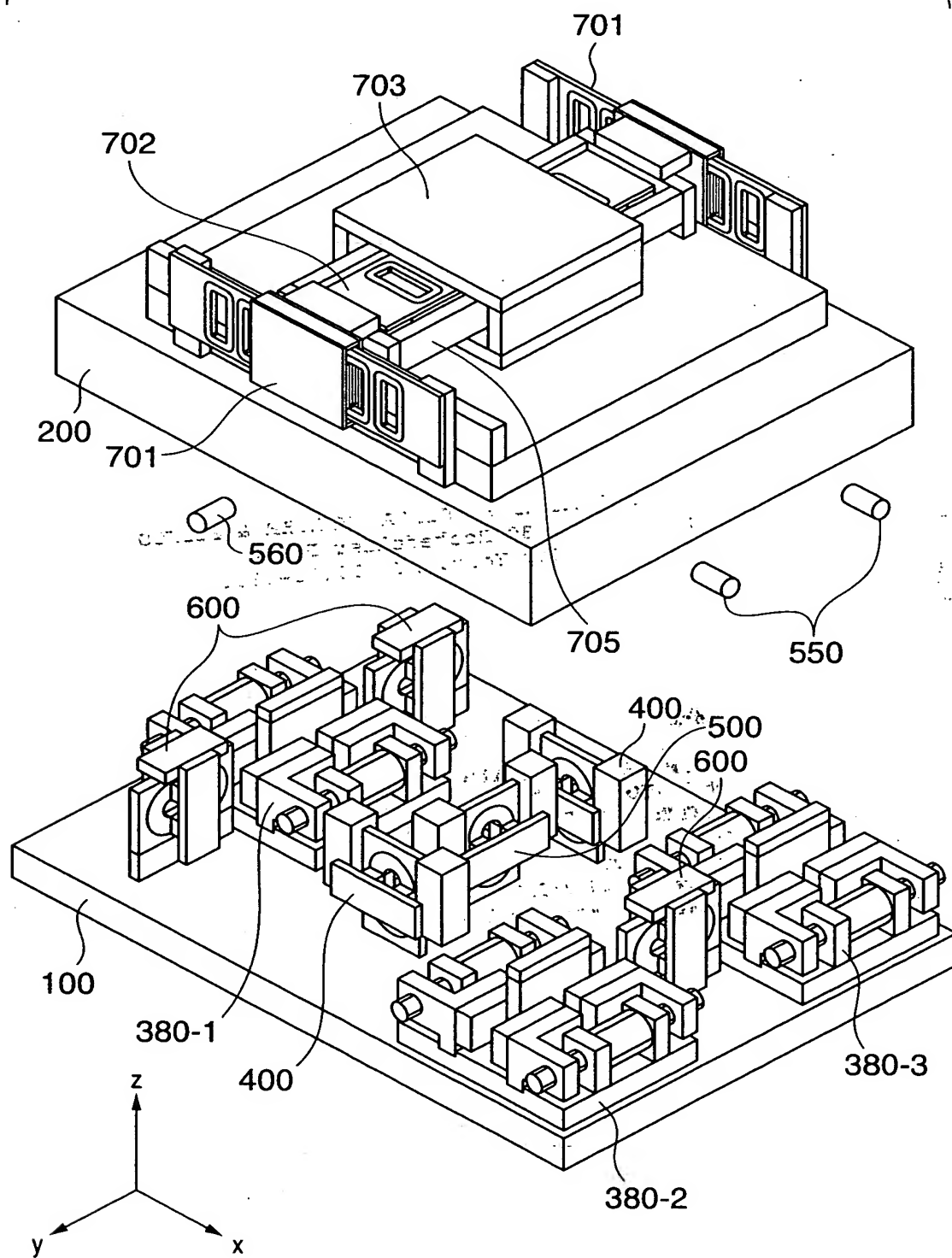


FIG. 9

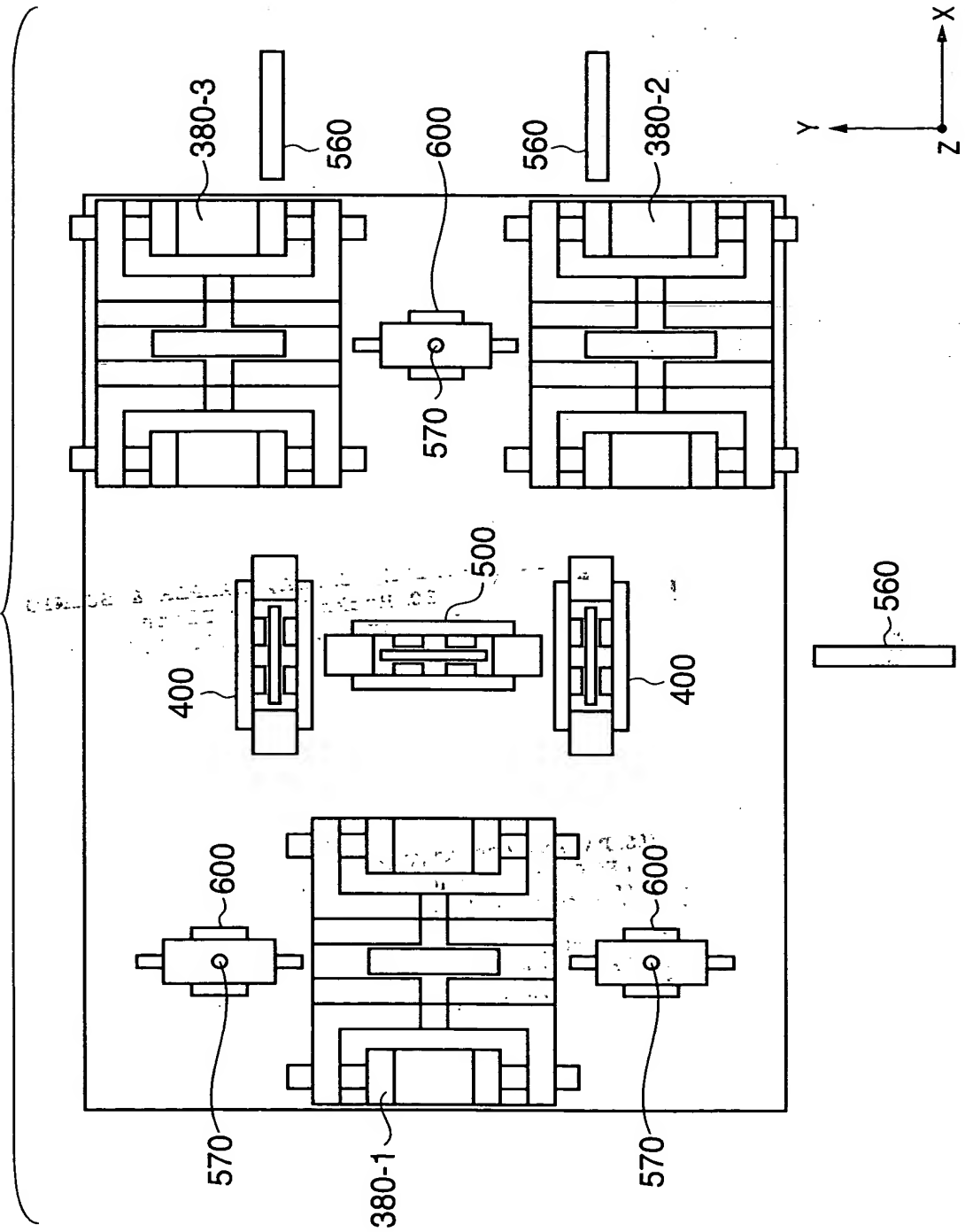


FIG. 10

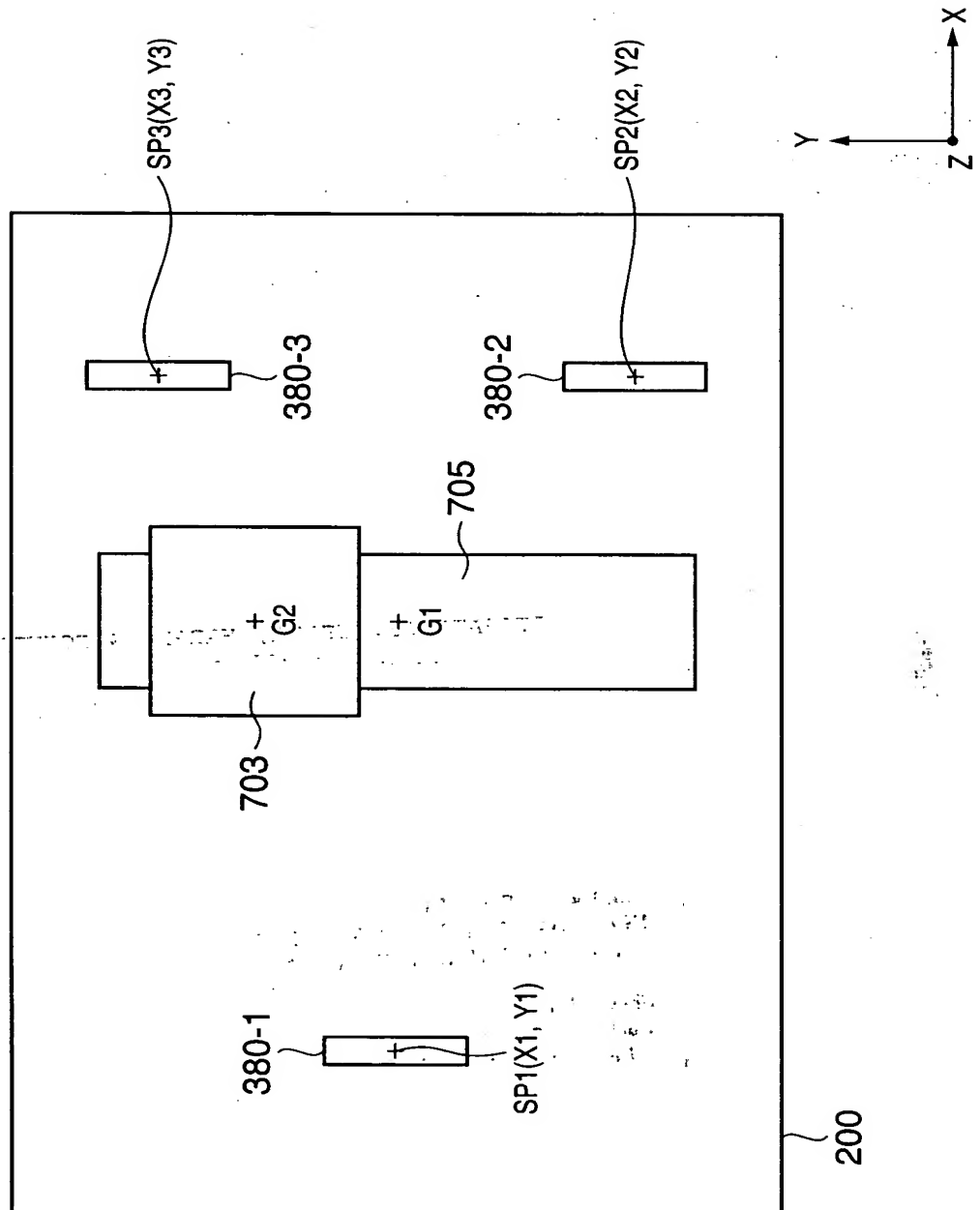


FIG. 11

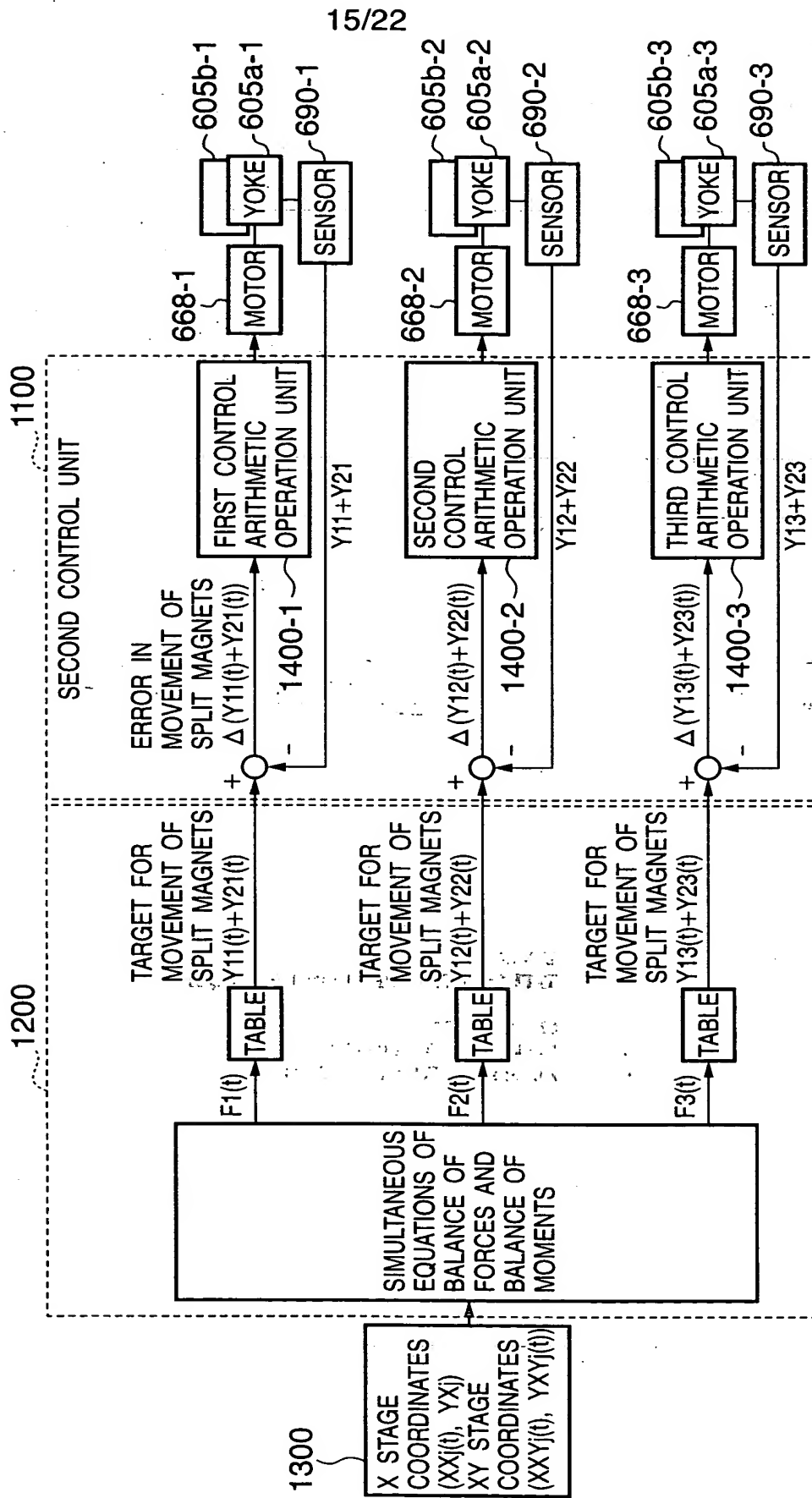


FIG. 12

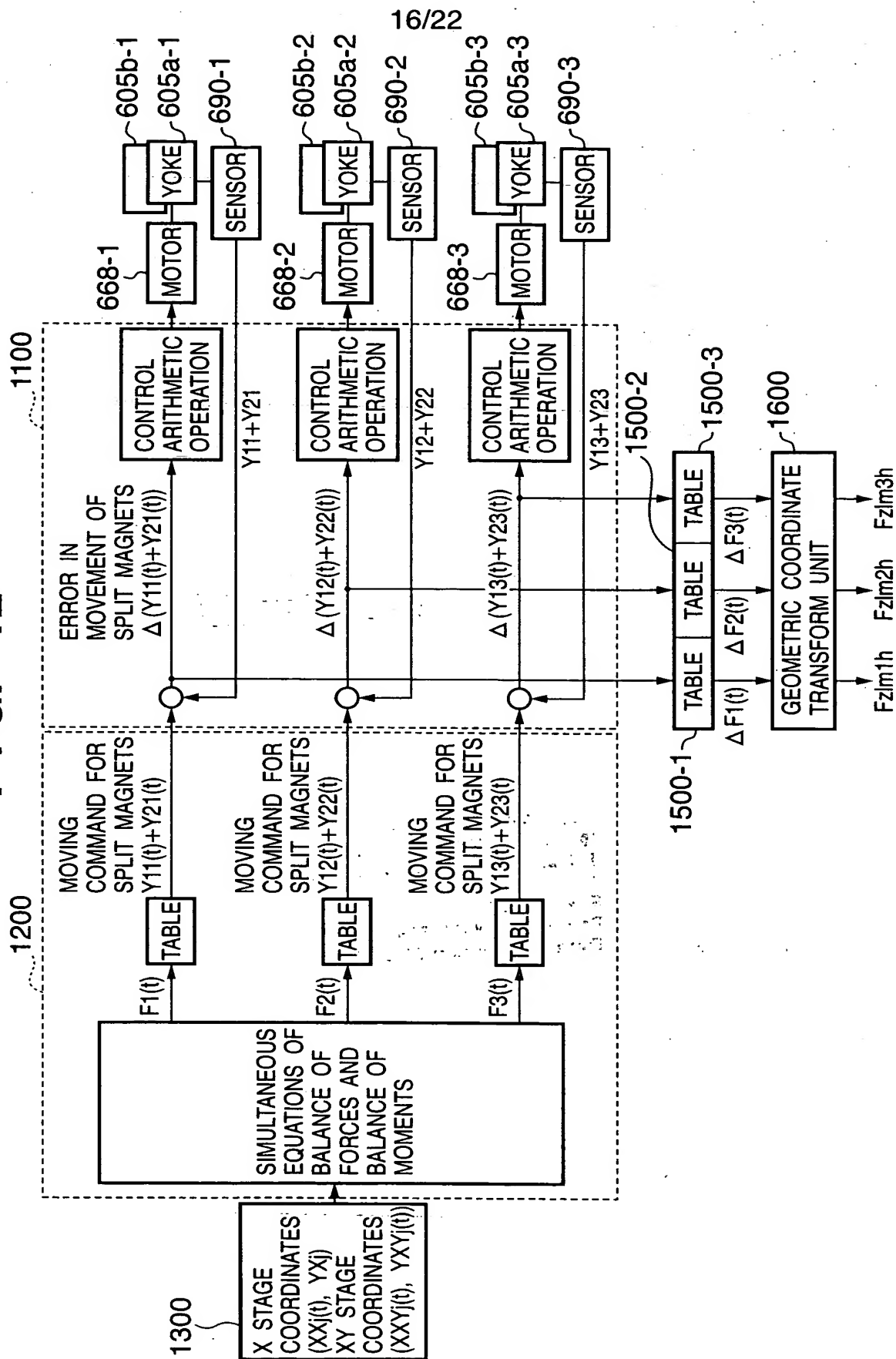


FIG. 13

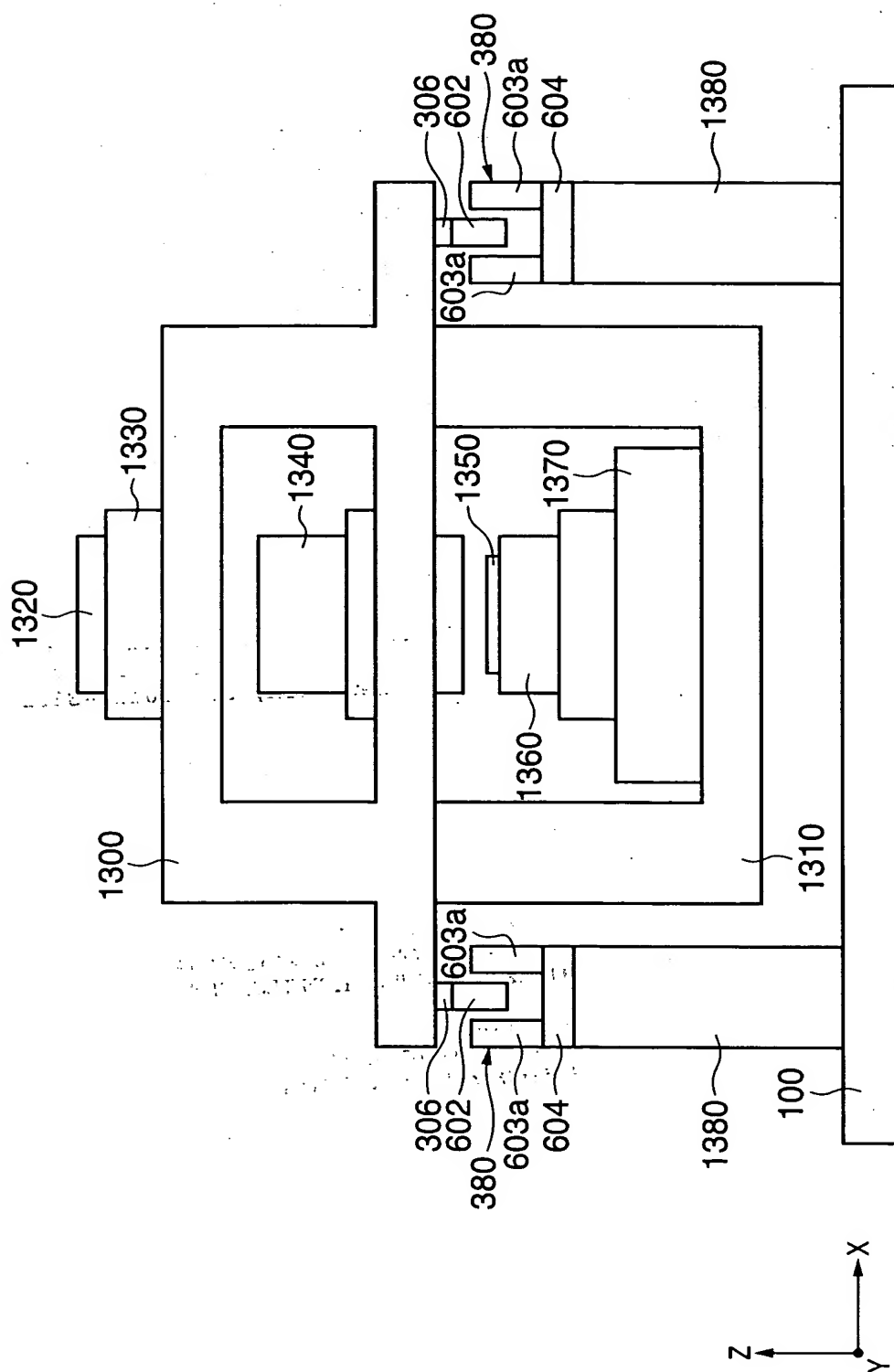


FIG. 14

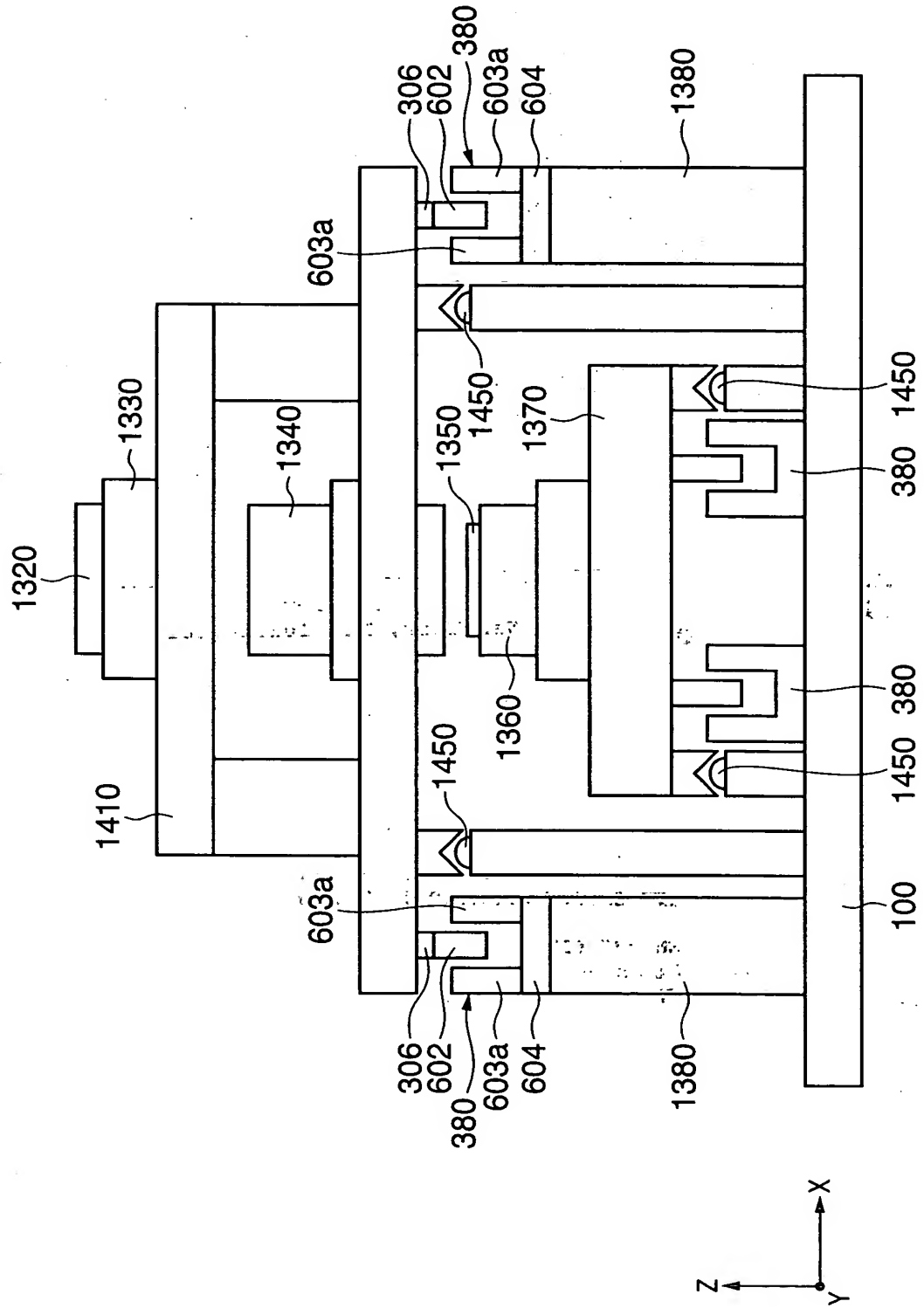


FIG. 15

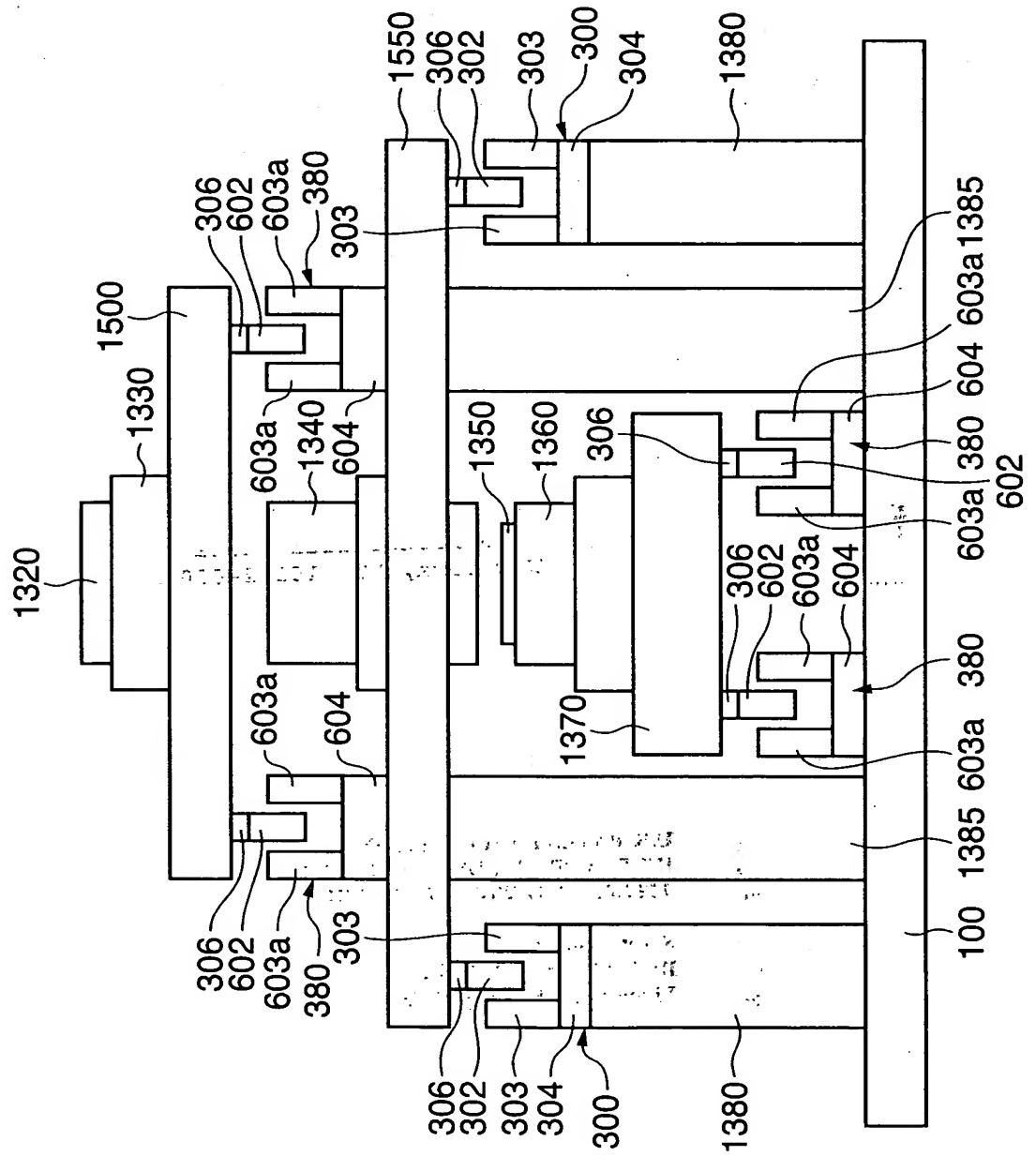


FIG. 16

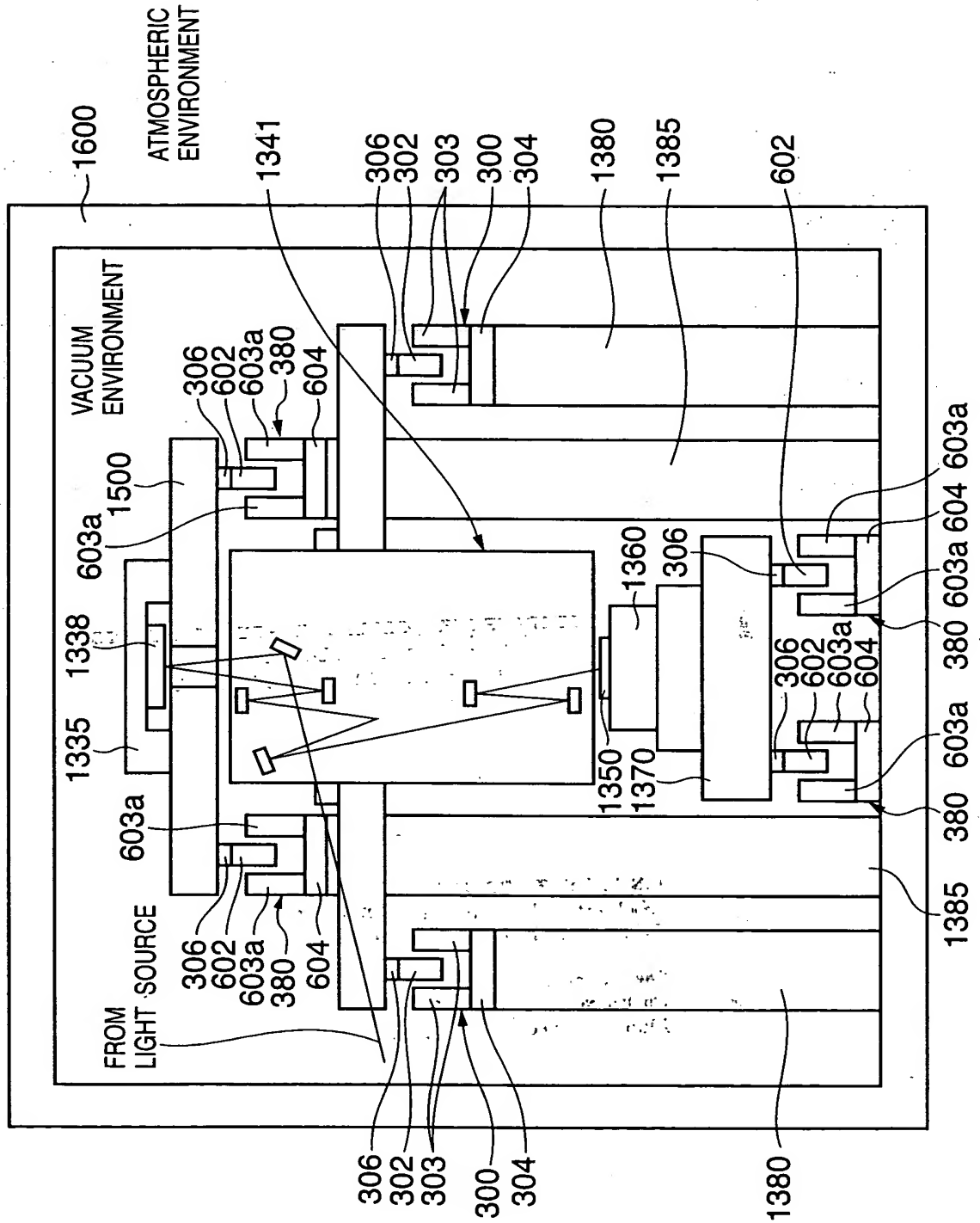
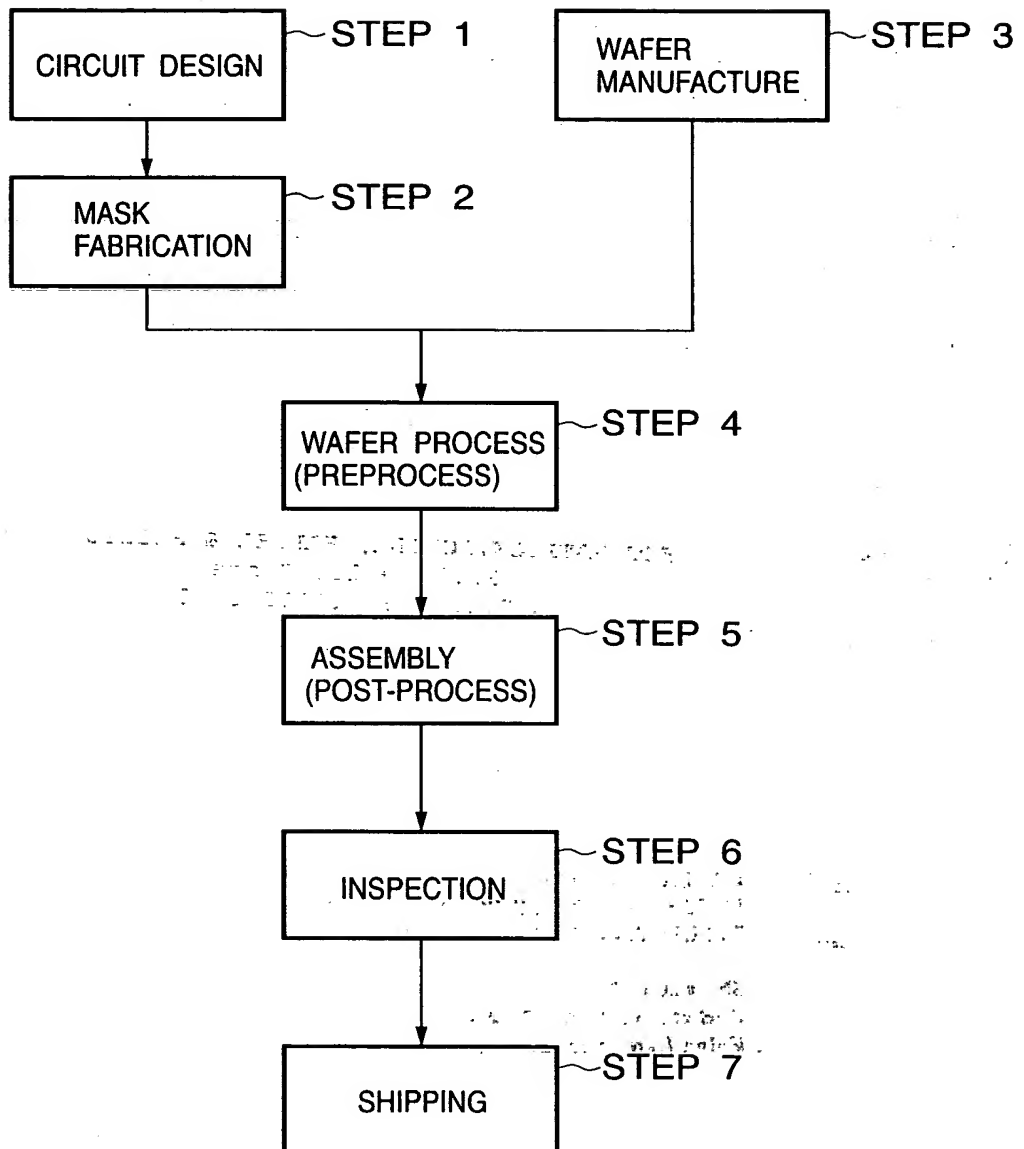


FIG. 17

FLOW OF SEMICONDUCTOR DEVICE MANUFACTURE

FIG. 18A

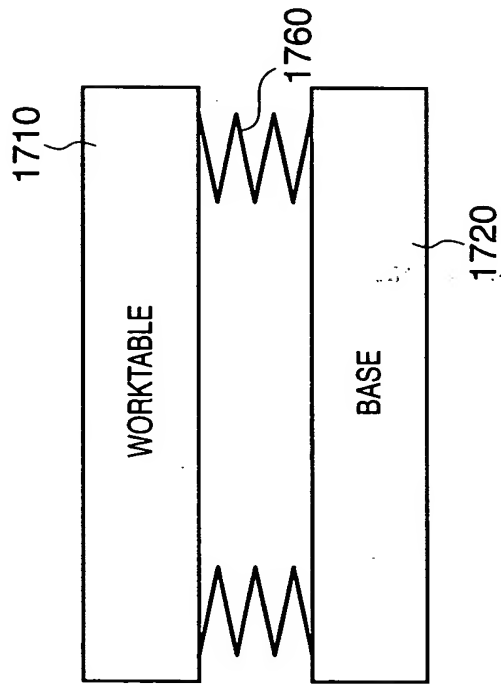


FIG. 18B

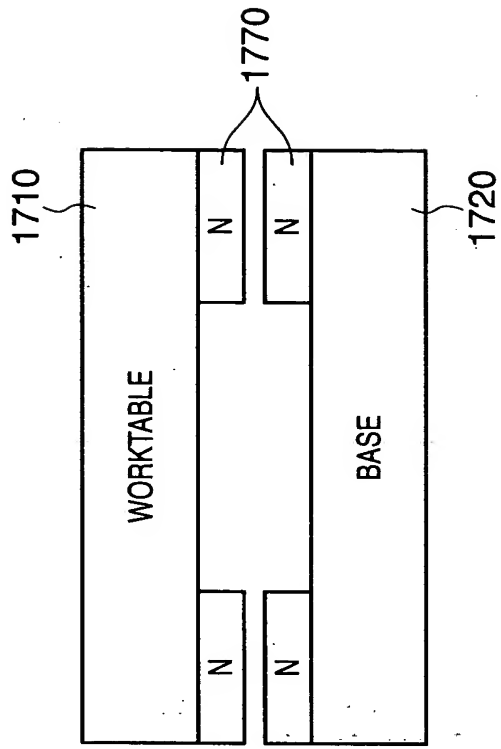


FIG. 18C

